

a' state and a low melt viscosity, and which may enable the easy release of a molded skin from a mold. ~

Please replace TABLE 7 beginning at column 11, line 1 (and overflowing into column 12), with the following rewritten Table 7:

TABLE 7						
parts by weight						
Component	Composi- tion 13	Composi- tion 14	Composi- tion 15	Composi- tion 16	Composi- tion 17	Composi- tion 18
polypropylene	56	56	56	56	56	56
Resin ²⁰	19	19	19	19	19	19
H-SBR ²¹						
SEPS ²²	9	9	--	--	9	--
EPR ²³	--	--	9	9	--	9
process oil ²⁴	12	12	12	12	12	12
organic peroxide ²⁵	0.1	0.3	0.3	0.4	--	--
pigment	4	4	4	4	4	4
Ca stearate	0.5	0.5	0.5	0.5	0.5	0.5
phenolic	0.1	0.1	0.1	0.2	0.1	0.1
antioxidant	0.1	0.1	0.1	0.2	0.1	0.1
phosphite antioxidant						

²⁰CHISSO POLYPRO K7750TM (a product of Chisso Corp.), MFR 230°C., 2.16 kgf): 45 g/10 min

²¹DYNARON 1320PTM (a product of Japan Synthetic Rubber), styrene content: 10 wt %, MFR (230°C., 2.16 kgf): 3.5 g/10 min

²²Styrene/ethylene/propylene/styrene block copolymer (SEPS), SEPTON 2063TM (a product of KURARAY), styrene content: 13 wt %, MFR (230°C., 2.16 kgf): 7 g/10 min

²³Ethylene/propylene rubber (EPR), EP914PTM (a product of Japan Synthetic Rubber), propylene content: 22 wt %, MFR(230°C., 2.16 kgf): 8.6 g/10 min

²⁴DIANATM Process Oil (a product of IDEMITSU KOSAN), PW: 380

²⁵Perhexa 25B40TM (a product of Nippon Oil and Fats Co., Ltd.), peroxide content: 40%, one-minute half-life temperature: 179°C.

In The Claims:

Please add new claims 27-49: